



Epson NX1032XS is set to revolutionise the transfer, testing and sorting of semiconductor chips. Developed using leading-edge robot technology, this IC test handler boasts significantly improved performance to support even the most demanding tests. With a maximum throughput of 20,000 chips per hour and the capacity to handle simultaneous multi-site tests, it is little wonder that the NX1032XS is recognised around the world as the industry's fastest, most accurate handler.



ENGINEERED FOR BUSINESS

Simultaneous Multi-site Tests

Maximum throughput of up to 20,000 chips per hour with simultaneous multi-site tests for 32 IC devices and high contact force of up to 4,800N.

Test Hand-independent Heat Press Method

Test chips at temperatures as high as 155°C and reduce jam recovery time.

Convenient Compatibility

Compatible with a wide range of changeover kits for the existing NS series (including adapter compatible changeover kits).



MODEL NUMBER	NX1032XS		
	16-site	32-site	
Devices Handled	QFP, TSOP, CSP, WLCSP, BGA, QFN, PLCC, LGA, PGA,		
	Min. 3×3 to Max. 50×50 (Lead pitch: 0.4mm or more) "		
Test Mode	N/A	32-site (8×4, X: 40mm pitch × Y: 60mm pitch)	
	16-site (8x2, X: 30mm pitch Y: 60mm pitch, 40mm pitch x Y: 60mm pitch) 8-site (4x2, X: 40mm pitch x Y: 60mm, X: 60mm pitch x Y: 60mm, X: 80mm pitch x Y: 60mm) 4-site (2x2, X: 80mm x Y: 60mm), (4x1, X: 40mm, 60mm, 80mm) 2-site (Socket pitch 80 mm) Single (use one side of the 2-site test) Non-standard pitches can be set by laying out the independent compliance unit with desired pitches		
Testing Area	344 × 146 mm	344 × 244 mm	
Standard Socket Pitch (mm)	X: 40mm Y: 60mm		
Heating Method	Heat Press Method		
Index Time '2 (common in Ambient and High Temperature modes)	Min. 0.38sec.		
	Approx. 0.42sec. (wide 4×2, 8×2 layout)	Approx. 2.05sec. (8×4 layout)	
	Approx. 2.21sec. (4,800N Option)	Approx. 4.35sec. (4,800N Option)	
Max. Contact Force	1,600N (Optional) or 4,800N (Standard)	3,200N (Optional) or 4,800N (Standard)	
Maximum Throughput (units per hour)			
Ambient Temperature	8×4 and 8×2 layouts: 20,000, 4×2 layout: 15,000		
High Temperature	8×4 and 8×2 layouts: 10,500, 4×2 layout:10,500		
Binning	Max. 6 bins (Auto 3, Manual 3)		
Tray	JEDEC (135.9 × 315.0 mm)		
Temperature Accuracy	50 - 90°C ±2°C 90 - 155°C ±3°C		
Hot Plate Size	220 × 380 mm ⁻³		
Power Requirement	Single Phase 200 - 240 V AC, 50/60 Hz, 6 kVA		
Handler Dimensions (D x W x H)	1,580 x 1,940 x 2,000 mm ⁻⁴		
Weight	Approx. 1,200kg		

©2016 Epson Singapore Pte Ltd. All Rights Reserved. Reproduction in part or in whole, without the written permission from Epson, is strictly prohibited.

EPSON and EXCEED YOUR VISION are registered trademarks of Seiko Epson Corporation.

All other product names and other company names used herein are for identification purposes only and are the trademarks or registered trademarks of their respective owners.

Epson disclaims any and all rights in those marks. Projected images shown herein are simulations. The actual product design and contents may vary. Specifications are subject to change without notice and may vary between countries. Please check with local Epson offices for more information.

Information correct as at March 2016

- Depends on the socket size and socket pitch.
- ² Depends on the socket installation height.
- Two hot plates are installed as standard. Up to two additional plates can be added as an option.
- Handle, signal tower, and LCD monitor are not included.

Compatibility of Socket Layout Kits

- 1. Socket Layout Kits (with heater) for NS8080HW and NS8160LS can be used.
- 2. Socket Layout Kits for chamber type Handler can be used for Ambient mode test.



Our IC handler plant was classified ISO9001, the international standard of quality assurance, in July 1997.



Our IC handler plant was classified ISO14001, the international standard of environmental management system in April 1998.



Safety Precaution | Please read associated manuals carefully before installing or using our robot products Always use products properly per guidelines in the manuals

• Please note that specifications and appearance of the product may change without notice for better performance.